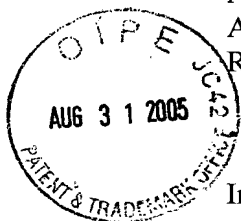


App. No. 10/607,613
Amend. Dated 8/29/05
Response To Action dated 6/10/05



PATENT

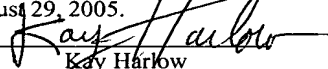
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of)	
Kiermasz et al.)	Examiner: Rachuba, Maurina T.
Application No: 10/607,613)	Art Unit: 3723
Filed: June 27, 2003)	Atty. Docket No: LAM2P421
For: PLATEN WITH DIAPHRAGM AND)	Date: August 29, 2005
METHOD FOR OPTIMIZING WAFER))	
POLISHING)	

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on August 29, 2005.

Signed


Kay Harlow

SUBMISSION UNDER 37 CFR 1.114

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Honorable Commissioner:

In response to the Final Office Action mailed June 10, 2005, which set a three month shortened period for response, please consider this as a Submission under 37 CFR 1.114, amend the captioned application as follows, and consider the following remarks.

Amendments to the claims start on page 2.

Remarks start on page 13.